

Advanced Circuit Materials



Rogers Corporation showcased several advanced circuit materials at the 2007 EuMW Week Show. These products are used in a wide range of high frequency applications, including the advanced packaging, antenna and power amplifier markets. Products displayed included new Enhanced Copper Bond Technology: This low profile copper technology provides tighter trace width tolerances, lower insertion loss and improved passive intermodulation at high operating frequencies. Thermoset Materials: Products such as RO4350B#153, RO4450B#153 RO4450D#153 laminates which offer low moisture absorption and low loss, as well as FR4 and lead-free multi-layer processing capabilities. In addition to advanced packaging materials and antenna grade materials.

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